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DATE OF MAILING 2/6/02

Our Case No. 9281-4274  
Client Reference No. S US00206

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: )  
Hideki Kondo )  
Serial No. To be Assigned )  
Filing Date: Herewith )  
For Waveguide for Microwave Device )

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Prior to examination of the above-identified application, please amend the application as follows:

**In the Claims**

Please rewrite Claim 1 as follows:

1. (Amended) A waveguide for a microwave device, comprising:  
a frame housing a high-frequency circuit therein; and  
a lid attached to a sidewall of the frame,  
wherein at least one of the frame and the lid has a waveguide groove  
formed therein and extending along a mating surface between the frame and the lid.

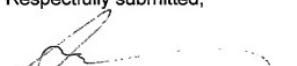
Please rewrite Claim 4 as follows:

4. (Amended) The waveguide according to Claim 2, wherein the sub-casing is arranged inside four sidewalls of the main casing and the main casing has a through-hole, through which the probe passes, formed in the sidewall to which the lid is attached.

## REMARKS

Applicant has rewritten Claims 1 and 4. The changes from the previous version to the rewritten version are shown in attached Appendix A, with strikethrough for deleted matter and underlining for added matter.

Respectfully submitted,



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**APPENDIX A**  
**Waveguide for Microwave Device**  
**Attorney Docket No. 9281-4274**  
**Inventor Hideki Kondo**

**In the Claims**

Please amend Claim 1 as follows:

1. (Amended) A waveguide for a microwave device, comprising:  
a frame housing a high-frequency circuit therein; and  
a lid attached to a sidewall of the frame,  
wherein at least one of the frame and the lid has a waveguide groove  
formed therein and extending along the mating surface between the frame and the  
lid.

Please amend Claim 4 as follows:

4. (Amended) The waveguide according to Claim 2, wherein the sub-casing is arranged inside the four sidewalls of the main casing and the main casing has a through-hole, through which the probe passes, formed in the sidewall to which the lid is attached.